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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
Hsiao-Wei Yeh	04/27/2007
Jen-Chieh Shih	04/27/2007
Jian-Hong Chen	04/27/2007

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Road 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code:	300-77	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11748322

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	24061.895	
NAME OF SUBMITTER:	Liem T. Do	

PATENT REEL: 019290 FRAME: 0599

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Total Attachments: 2

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PATENT REEL: 019290 FRAME: 0600

Docket No.: 2006-1038 / 24061.895

Customer No.: 42717

ASSIGNMENT

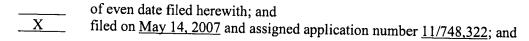
WHEREAS,	we,
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(1)	Hsiao-Wei Yeh	of	No. 6, Alley 8, Lane 520, Syuefu Rd. Jhudong Township, Hsinchu County 310, Taiwan, R.O.C.
(2)	Jen-Chieh Shih	of	16F, No. 280, Dong Sec. 1, Guangming 6th Rd. Jhubei City, Hsinchu County 302, Taiwan, R.O.C.
(3)	Jian-Hong Chen	of	No. 5, Alley 2, Lane 186, Kung-Yuan Rd. Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

MATERIAL AND METHOD FOR PHOTOLITHOGRAPHY

for which we have executed an application for Letters Patent of the United States of America,



WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C., Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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PATENT REEL: 019290 FRAME: 0601

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor	Name:

Hsiao-Wei Yeh

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Hsian-Wei Yeh

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Jen Chieh Shih Inventor Signature

Inventor Name:

Jian-Hong Chen

Residence Address:

No. 5, Alley 2, Lane 186, Kung-Yuan Rd.

Hsin-Chu, Taiwan, R.O.C.

Dated:

2007/4/21

Inventor Signature

R-895 - Assignment 4-26-07

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P.08/10 RECORDED: 05/14/2007